



8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

Description

The 74HC164 is a serial input 8-bit edge-triggered shift register that has outputs from each of eight stages.

SERIAL DATA INPUT PINS

The serial input data is entered at pin SDA or pin SDB as these are logically ANDED. Either input could be used as an active HIGH enable with data entry on the other pin. If a single input is desired, the pins can be tied together or the unused input can be tied HIGH.

DATA ENTRY

Data is shifted into Q0 from the serial input pins on each LOW to HIGH transition of the CP pin. Also during the CP edge the data is transferred from each Qn to Qn+1. The serial data on pins DSA and DSB must be stable before and after the CP rising edge to meet the set-up and hold timing requirements.

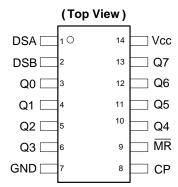
RESET

When asserted LOW the Master Reset (MR) pin sets all Qn to LOW. This action does not depend on the condition of serial input or clock pins. The MR must be asserted HIGH for a recovery time before the next CP positive edge pulse.

Features

- Wide Supply Voltage Range from 2.0V to 6.0V
- Sinks or Sources 4mA at V_{CC} = 4.5V
- CMOS Low Power Consumption
- Schmitt Trigger Action at all Inputs
- ESD Protection Exceeds JESD 22
 - 200-V Machine Model (A115)
 - 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Range of Package Options SO-14 and TSSOP-14
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignments



SO-14 / TSSOP-14 / PDIP-14

Applications

- General Purpose Logic
- Wide Array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks
 - Computer Peripherals, Hard Drives, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Device Ordering Information is on Page 7



Pin Descriptions

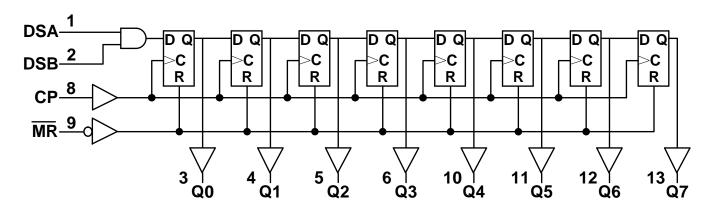
Pin Number	Pin Name	Function	
1	DSA	Serial Data Input	
2	DSB	Serial Data Input	
3	Q0	Data Output	
4	Q1	Data Output	
5	Q2	Data Output	
6	Q3	Data Output	
7	GND	Ground	
8	СР	Clock Pulse –Positive Edge Triggered	
9	MR	Master Reset - Asynchronous	
10	Q4	Data Output	
11	Q5	Data Output	
12	Q6	Data Output	
13	Q7	Data Output	
14	Vcc	Supply Voltage	

Function Table (Note 4)

		In	Output			
Mode MR		СР	DSA	DSB	Q0	Q1-Q7
Reset	L	Х	Х	Х	L	L
	Н	↑	L	Х	L	Qn←Qn-1 (n= 1 to7)
Shift	Н	↑	Х	L	L	Qn←Qn-1 (n= 1 to7)
	Н	↑	Н	Н	Н	Qn←Qn-1 (n= 1 to7)

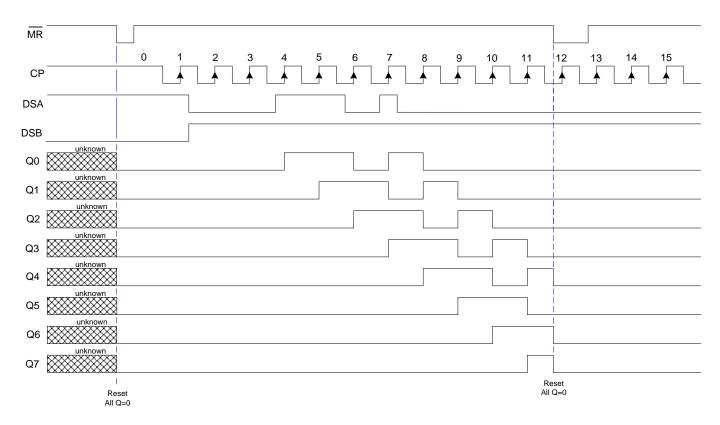
Note: 4. Signals asserted on DSA and DSB must be in place longer than Tsu (set-up time) before CP occurs and remain in place Thold (hold time) after CP.

Logic Diagram





Timing Diagram



5. All Q values are reset to LOW when \overline{MR} goes low. \overline{MR} is asynchronous and overrides all other signals. 6. Serial data supplied at DSA and DSB is ANDED and transferred to Q0 on positive edge of CP. Notes:

Absolute Maximum Ratings (Note 7) (TA = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to +7.0	V
Vı	Input Voltage Range (Note 8)	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < -0.5V or Vi > V _{CC} +0.5V	±20	mA
I _{OK}	Output Clamp Current $V_O < -0.5V$ or $V_O > V_{CC} +0.5V$	±20	mA
lo	Continuous Output Current -0.5V < V _O V _{CC} +0.5V	+/- 25	mA
Icc	Continuous Current through Vcc	50	mA
I _{GND}	Continuous Current through GND	-50	mA
T_J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

7. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should Notes: be within recommend values.

8. Input Voltage cannot exceed Vcc to the extent the maximum clamp current is exceeded.



Recommended Operating Conditions (Note 9) (T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage	_	2.0	6.0	V
VI	Input Voltage	_	0	V _{CC}	V
Vo	Output Voltage	_	0	Vcc	V
		V _{CC} = 2.0V	_	625	
Δt/ΔV	Δt/ΔV Input Transition Rise or Fall Rate	$V_{CC} = 4.5V$	_	140	ns/V
		V _{CC} = 6.0V	_	85	
TA	Operating Free-Air Temperature	_	-40	+125	°C

Note: 9. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test	V _{CC}	T	_A = +25°C		T _A = -4 +85		T _A = -40°C	to +125°C	Unit
,		Conditions		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
		_	2.0V	1.5	1.2	_	1.5	_	1.5	_	
V _{IH}	High-level Input Voltage	_	4.5V	3.15	2.4	_	3.15	_	3.15	_	V
	Voltage	_	6.0V	4.2	3.2	_	4.2	_	4.2	_	-
		_	2.0V	_	0.8	0.5	_	0.5	_	0.5	
V_{IL}	Low-level Input Voltage	_	4.5V	_	2.1	1.35	_	1.35	_	1.35	V
	Voltage	_	6.0V	_	2.8	1.8	_	1.8	_	1.8	
		$I_{OH} = -20\mu A$	2.0V	1.9	2.0	_	1.9	_	1.9	_	
		I _{OH} = -20μA	4.5V	4.4	4.5	_	4.4	_	4.4	_	
V _{OH}	High-level Output Voltage	I _{OH} = -20μA	6.0V	5.9	6.0	_	5.9	_	5.9	_	V
	Output Voltage	$I_{OH} = -4.0 \text{mA}$	4.5V	3.98	4.32	_	3.84	_	3.7	_	
		I _{OH} = -5.2mA	6.0V	5.48	5.81	_	5.34	_	5.2	_	1
		I _{OL} = 20μA	2.0V	_	0	0.1	_	0.1	_	0.1	
		I _{OL} = 20μA	4.5V	_	0	0.1	_	0.1	_	0.1	
V_{OL}	Low-level Output Voltage	I _{OL} = 20μA	6.0V	_	0	0.1	_	0.1	_	0.1	V
	Output voltage	I _{OL} = 4mA	4.5V	_	0.15	0.26	_	0.33	_	0.4	
		I _{OL} = 5.2mA	6.0V	_	0.15	0.26	_	0.33	_	0.4	•
II	Input Current	V _I =GND or V _{CC}	6.0V	_	_	±0.1	_	± 1	_	± 1	μA
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0A$	6.0V	_	_	8.0	_	80		160	μA



Switching Characteristics

Symbol /	<u> </u>	Test	.,		T _A = +25°C		-40°C to	+85°C	-40°C to	+125°C	Unit
Parameter	Pins	Conditions	V _{cc}	Min	Тур.	Max	Min	Max	Min	Max	
			2.0 V	6	23	_	5	_	4	_	
f _{MAX}	0.5	Figure 1	4.5 V	30	71	_	24	_	20	_	
Maximum Frequency	CP		5.0 V	_	78	_	_		_	_	MHz
Frequency			6.0 V	35	85	_	28	_	24	_	
	СР		2.0 V	80	14	_	100		120	_	
	HIGH or	Figure 1	4.5 V	16	5	_	20		24	_	ns
	LOW		6.0 V	14	4		17	_	20	_	
t _W Pulse Width			2.0 V	60	17	_	75		90	_	
Fuise Width	MR LOW	Figure 1	4.5 V	12	6	_	15		18	_	no
	WIR LOW	riguie i	6.0 V	10	5		13	_	15	_	ns
			2.0 V	60	8	_	75		90	_	
t _{SU}	DSA or DSB to CP	Figure 1	4.5 V	12	3	_	15		18	_	ns
Set-up Time	D3B 10 CF		6.0 V	10	2	_	13		15	_	
,	501		2.0 V	4	-6		4	_	4	_	
t _H Hold Time	DSA or DSB to CP	Figure 1	4.5 V	4	-2		4		4	_	ns
rioid riirie	0000		6.0 V	4	-2		4		4	_	
			2.0 V		41	170	_	215	_	255	
t _{PD}	CP to Qn	Figure 1	4.5 V	_	15	34	_	43	_	51	no
Propagation Delay	CP to QII		5.0 V	_	12	_	_	_	_		ns
Dolay			6.0 V	_	12	29	—	37	_	43	
			2.0 V	60	17	_	75	_	90	—	
t _{rec} Recovery Time	MR to CP		4.5 V	12	6		15		18	—	ns
Recovery Time			6.0 V	10	5	_	13	_	15	—	
t_{PHL}			2.0 V	_	39	140	—	175	_	210	
HIGH to LOW Propagation Delay MR to Qn	Figure 1	4.5 V	_	14	28	_	35	_	42	ne	
		5.0 V	_	11	_	—		_		ns	
Delay			6.0 V	_	11	24	_	30		36	
t _T			2.0 V	_	19	75	_	95	_	110	
Transition	All signals	Figure 1	4.5 V		7	15	_	19		22	ns
Time			6.0 V	<u> </u>	6	13	_	16	_	19	

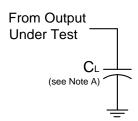
Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V _{CC} = 6V	Unit
		rest conditions	Тур	Oilit
C _{pd}	Power Dissipation Capacitance per Gate	f = 1 MHz	40	pF
Cı	Input Capacitance	$V_I = V_{CC} - or GND$	3.5	pF

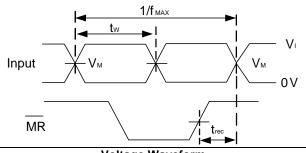
Vcc



Parameter Measurement Information



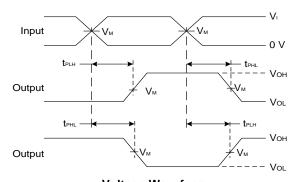
V _{cc}	Inputs		V _M	C _L
	Vı	t _r /t _f		
2.0V	V _{cc}	6ns	V _{CC} /2	50pF
4.5V	V _{cc}	6ns	V _{CC} /2	50pF
5.0V	V _{cc}	6ns	V _{CC} /2	15pF
6.0V	V _{cc}	6ns	V _{CC} /2	50pF



Timing Input 0V Vcc Data Input 0V

Voltage Waveform **Pulse Duration and Recovery Time**

Voltage Waveform Set-up and Hold Times



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

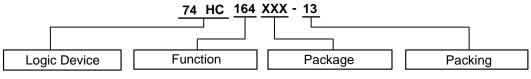
A. Includes test lead and test apparatus capacitance. Notes:

- B. All pulses are supplied at pulse repetition rate ≤10 MHz.
 C. Inputs are measured separately, one transition per measurement.
- D. t_{PLH} and t_{PHL} are the same as $t_{PD.}$
- E. Transition times t_t, t_{tlh}, t_{thl} are measured from the 10% to 90% or 90% to 10% of the appropriate waveform.

Figure 1 Load Circuit and Voltage Waveforms



Ordering Information



74: Logic Prefix 2.0V to 6.0V HC:

Family

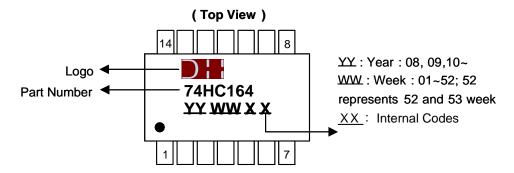
164:8-Bit Serial In Parallel Out Shift Register S14: SO-14 T14: TSSOP-14 D14: PDIP-14

-13:13" Tape & Reel

Device	Backago Codo	Backage Code Backaging	Packing		
Device	Package Code	Packaging	Quantity	Part Number Suffix	
74HC164S14-13	S14	SO-14	2,500/Tape & Reel	-13	
74HC164T14-13	T14	TSSOP-14	2,500/Tape & Reel	-13	
74HC164D14	D14	PDIP-14	TUBE	No Suffix	

Marking Information

(1) SO-14, TSSOP-14, PDIP-14



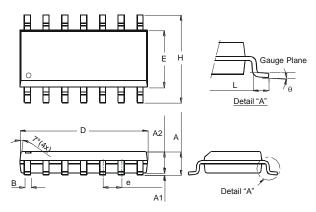
Part Number	Package
74HC164S14-13	SO-14
74HC164T14-13	TSSOP-14
74HC164D14	PDIP-14



Package Outline Dimensions (All dimensions in mm.)

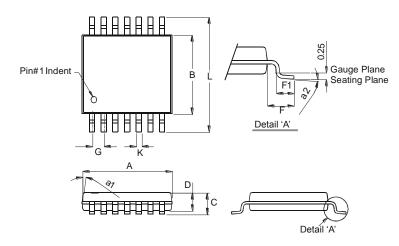
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

Package Type: SO-14



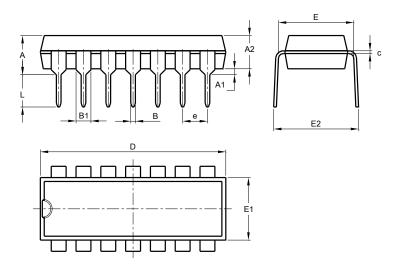
	SO-14						
Dim	Min	Max					
Α	1.47	1.73					
A1	0.10	0.25					
A2	1.45	Тур					
В	0.33	0.51					
D	8.53	8.74					
Е	3.80	3.99					
е	1.27	Тур					
Н	5.80	6.20					
L	0.38	1.27					
θ	0°	8°					
All Di	All Dimensions in mm						

Package Type: TSSOP-14



•	TSSOP-14						
Dim	Min	Max					
a1	7° (4X)					
a2	0°	8°					
Α	4.9	5.10					
В	4.30	4.50					
С	_	1.2					
D	0.8	1.05					
F	1.00	Тур					
F1	0.45	0.75					
G	0.65	Тур					
K	0.19	0.30					
١	6.40 Typ						
All Dir	nensions	s in mm					

Package Type: PDIP-14



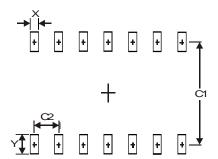
PDIP-14		
Dim	Min	Max
Α	3.710	4.310
A1	0.510	-
A2	3.200	3.600
В	0.380	0.570
B1	1.524 (BSC)	
С	0.204	0.360
D	18.800	19.200
E	6.200	6.600
E1	7.320	7.920
E2	8.400	9.000
е	2.540 (BSC)	
L	3.000	3.600
All Dimensions in mm		



Suggested Pad Layout

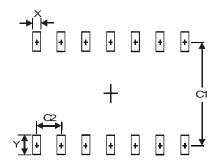
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)	
Х	0.45	
Y	1.45	
C1	5.9	
C2	0.65	



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